

# Circuits Rump Session

Organizers: J. Barth, IBM  
J. Yamaoka, Hitachi

## **R1: A Role for VLSI in Green Technology?**

Organizers: J. Rabaey, University of California, Berkeley  
M. Nomura, Renesas

Moderator: J. Rabaey, University of California, Berkeley

Green technology is all the rage (as is quite obvious from the investment community). One way to reduce our overall carbon footprint is to rethink in a profound way how we produce, transport, store and consume energy in a profound way. Information technology (supported by advanced networks of semiconductor devices) may have to play a major role in that process. In this panel, we explore a number of visions from different business segments of how this may transpire, what is needed to really make it happen, and what the roadblocks may be.

*Panelists:*

D. Freeman, Texas Instruments  
M. Kondo, AIST

C. Lampe-Onnerud, Boston-Power  
Y. Nishibe, Toyota

## **R2: Mixed Signal IP – Make vs. Buy**

Organizers: S. Nataragan, TSMC  
K. Kajigaya, Elpida

Moderator: P. Rickert, Texas Instruments

With the increasing use of foundries across the industry, the question of when to make IP vs. when to buy IP is becoming more important. This panel is focused on the chip manufacturer's choice of design vs buy for complex mixed-signal IP. Panelists will represent larger chip vendors, fab-less IP providers and mixed signal IP consumers.

*Panelists:*

K. Arimoto, Renesas  
J. Greco, nVidia  
S-T Juang, TSMC

M. Keating, Synopsis  
C. Mater, Qualcomm  
S. Segars, ARM